### LN59, LNA2702L (LN59L)

#### GaAs Bi-directional Infrared Light Emitting Diodes

For light source of VCR (VHS System)

#### Features

- Two-way directivity
- High-power output, high-efficiency: P<sub>O</sub> = 1.8 mW (min.)
- Small resin package
- Long lifetime, high reliability
- Long lead wire type (LNA2702L)

#### Applications

- Light source for tape end sensor of VCR and video camera recorder of VHS system
- Light source for 2-bit photo sensor

#### ■ Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Ratings	Unit	
Power dissipation	$P_{D}$	75	mW	
Forward current (DC)	$I_{F}$	50	mA	
Pulse forward current	I <sub>FP</sub> *	11	A	
Reverse voltage (DC)	$V_R$	3	V	
Operating ambient temperature	Topr	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	- 40 to +100	°C	

<sup>\*</sup> f = 100 Hz, Duty cycle = 0.1 %

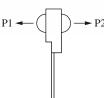
# **LN59** Unit: mm 1.8±0.2 ø2.5±0.2 2-R1.25±0.1 2-0.8 max. $15.3\pm1.0$ 1: Anode LNA2702L 1: Anode

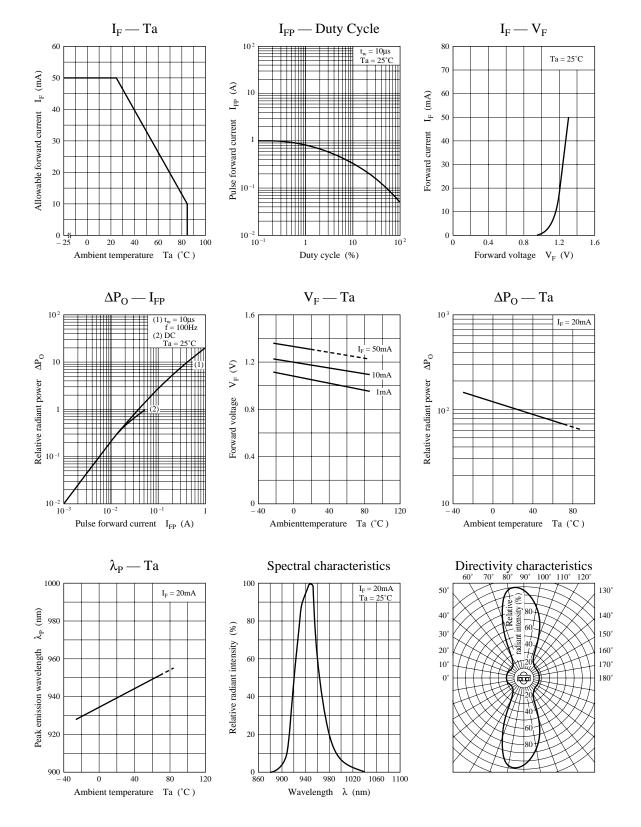
#### ■ Electro-Optical Characteristics (Ta = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Radiant power	Po*	$I_F = 50 \text{mA}$	1.8			mW
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 20 \text{mA}$		950		nm
Spectral half band width	Δλ	$I_F = 20 \text{mA}$		50		nm
Forward voltage (DC)	$V_{\rm F}$	$I_F = 50 \text{mA}$		1.3	1.5	V
Reverse current (DC)	I <sub>R</sub>	$V_R = 3V$			10	μΑ
Capacitance between pins	$C_{t}$	$V_R = 0V$ , $f = 1MHz$		35		pF

<sup>\*</sup> Radiant power Po shows each value of radiant flux P1 and P2 in two directions.







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## Gallium arsenide material (GaAs) is used in this product.

Therefore, do not burn, destroy, cut, crush, or chemically decompose the product, since gallium arsenide material in powder or vapor form is harmful to human health

Observe the relevant laws and regulations when disposing of the products. Do not mix them with ordinary industrial waste or household refuse when disposing of GaAs-containing products.

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